

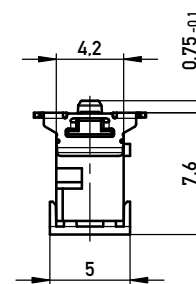
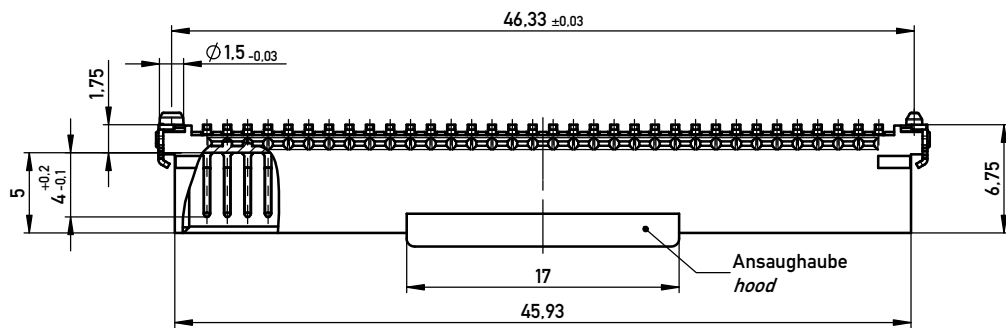
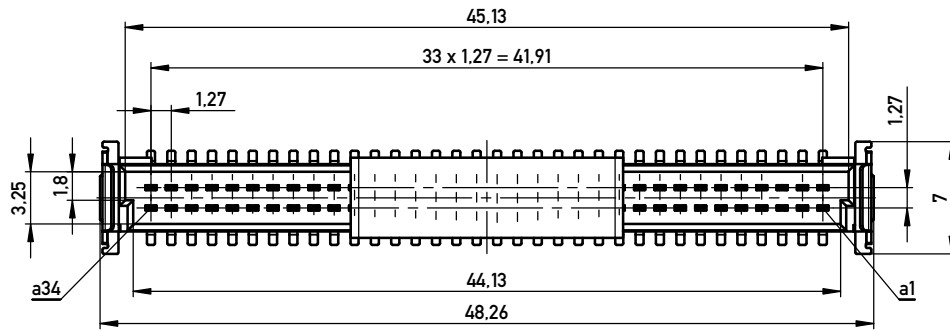
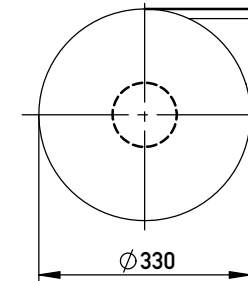
Anforderungsstufe 1
Performance Level 1

Kontaktbereich vergoldet
Mating Area gold plating

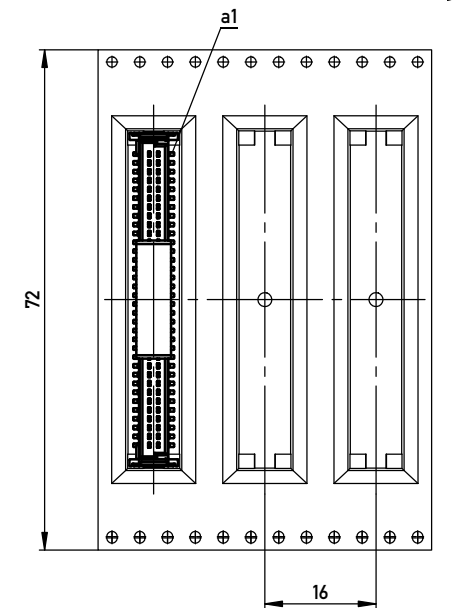
Anschlussbereich verzinkt 4-6 µm
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
Coplanarity Area of Termination ≤ 0,1 mm

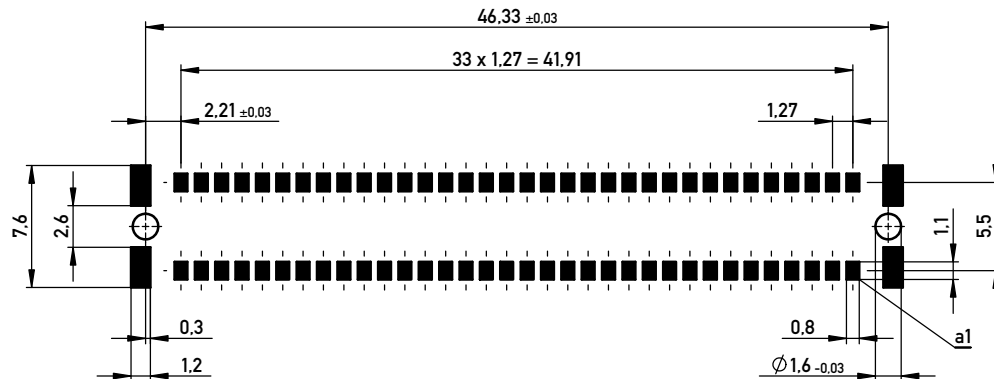
Verpackt im Gurt nach DIN IEC 60286-3
Tape on Reel Packaging according to DIN IEC 60286-3
Verpackungseinheit: 280 Stück
Packaging unit: 280 pcs





Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT



BA 8-13 - 8mm Bauhöhe
type 8-13 - Low Profile

| | | | | |
|--|---|--------------|---|---------|
| Information: All rights reserved. Only for Information. To ensure that this is the latest version of this drawing, please contact one of the ERNI companies before using. | Tolerances  All Dimensions in mm | Scale 3:1 | Designation Messertl. SMC-Q 68-SMD-BA8-13 <i>Male SMC-Q 68-SMD-type8-13</i> | |
| | Subject to modification without prior notice. Drawing will not be updated. | |  www.ERNI.com 244839 Class SMCQ | |
| e Index | 30.06.2015 Date | | | I A3 |

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